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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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2SD2178

Silicon NPN epitaxial planar type

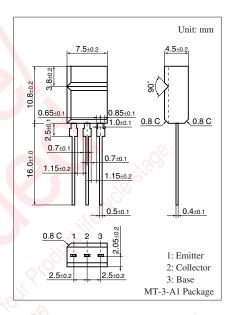
For low-frequency output amplification

■ Features

- ullet Low collector-emitter saturation voltage $V_{\text{CE(sat)}}$
- Large collector current I_C

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	50	V	
Collector-emitter voltage (Base open)	V _{CEO}	50	V	
Emitter-base voltage (Collector open)	V _{EBO}	5	V	
Collector current	I_{C}	2	A	
Peak collector current	I _{CP}	3	A	
Collector power dissipation	P_{C}	1.5	W	
Junction temperature	T_{j}	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	



■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_C = 10 \mu\text{A}, I_E = 0$	50	8	0	V
Collector-emitter voltage (Base open)	V _{CEO}	$I_C = 1 \text{ mA}, I_B = 0$	50			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = 10 \mu\text{A}, I_C = 0$	5	5		V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 20 \text{ V}, I_{E} = 0$.0		0.1	μΑ
Forward current transfer ratio	h _{FE1} *	$V_{CE} = 2 \text{ V}, I_{C} = 200 \text{ mA}$	120		340	_
	h _{FE2}	$V_{CE} = 2 \text{ V}, I_{C} = 1 \text{ A}$	80			
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = 1 \text{ A}, I_B = 50 \text{ mA}$		0.15	0.30	V
Base-emitter saturation voltage	V _{BE(sat)}	$I_C = 1 \text{ A}, I_B = 50 \text{ mA}$		0.9	1.2	V
Transition frequency	f_T	$V_{CB} = 10 \text{ V}, I_E = -50 \text{ mA}, f = 200 \text{ MHz}$		150		MHz
Collector output capacitance (Common base, input open circuited)	C _{ob}	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		23	35	pF

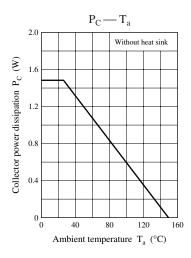
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

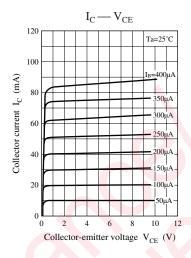
2. *: Rank classification

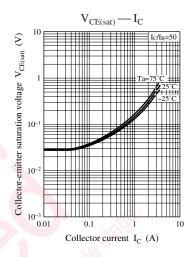
Rank	R	S
$h_{\rm FE1}$	120 to 240	170 to 340

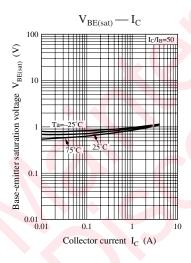
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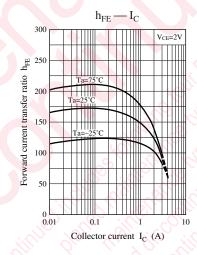
Panasonic

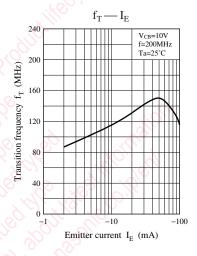


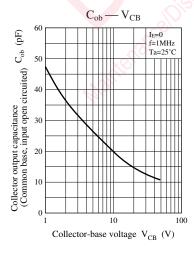


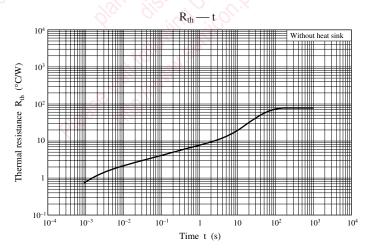












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